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IC Packaging Markets

2012 Global Report Series

Handheld electronic gadgets such as the iPhone and tablets are all the rage, with demand outpacing much of the rest of the economy. With the IC package determining the footprint on the printed circuit board (PCB), it is advances in the IC packaging technology which have enabled these extraordinarily miniaturized products to be developed and perfected.

New Venture Research (NVR) is pleased to announce its continuing coverage of the IC packaging market with two reports in 2012, ***The Worldwide IC Packaging Market***, and ***Advanced IC Packaging Technologies, Materials, and Markets***. Each report has a different focus, thus allowing the user to analyze the IC packaging market from a number of angles, and combine that information to meet individual research needs.

The first report, **The Worldwide IC Packaging Market**, presents NVR's annual forecast for each of the major package families by semiconductor product type (2010-2016). This information is then totaled by package type. The report also presents NVR's continuing, extensive coverage of the packaging contractor market.

The second report , **Advanced IC Packaging Technologies, Materials, and Markets,** analyzes critical advanced IC packaging methods, primarily aimed at the mobile handheld consumer market, while also including some leading material analysis of IC packaging sets.

The IC Packaging series will provide you with an effective tool for assessing your future in this market. Please review each report's summary Table of Contents on the following page.

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New Venture Research
337 Clay St., Suite 101
Nevada City, CA 95959
Tel: (408) 244-1100 Fax: (408) 864-2138
www.newventureresearch.com; kwilliams@newventureresearch.com

The Worldwide IC Packaging Market

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Advanced IC Packaging Technologies, Materials, and Markets

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About the Author

Sandra Winkler has been an industry analyst since 1988, previously with Electronic Trend Publications and now with New Venture Research Corp. She has authored more than 30 widely cited reports on the semiconductor packaging industry. She writes for *Chip Scale Review* magazine, and is on the executive planning committee of the IEEE/CPMT Santa Clara Valley Chapter, serving as Luncheon Program Chair. Ms. Winkler holds an MBA from Santa Clara University.